

TEMPERATURE ADJUSTING DEVICE AND POLISHING DEVICE

ABSTRACT

An object of the present invention is to improve in-plane uniformity in polishing in a polishing device.

A temperature adjusting device for adjusting temperature of a rotating polishing pad comprises: a heat conductor that can contact with a top face of the polishing pad; an arm for holding the heat conductor above the polishing pad; column members formed to stand on a top face of the heat conductor, comprising an upstream-side column member and a downstream-side column member arranged at a position at an upstream/downstream side of rotation of the polishing pad; and overhung members extending, from the upstream-side column member and the downstream-side column member, in directions that are parallel to the top face of the heat conductor; wherein the overhung members can contact with a top face of the arm.

Representative drawing: Fig. 2